

GTXO-566 - 3V & 5V SM (VC)TCXO Clipped Sine					
Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Base	Board	BT resin		19.000	18.05
	Board	Glass Fibre	65997-17-3	38.000	36.11
	Pattern	Au	7440-57-5	0.100	0.10
	Pattern	Cu	7440-50-8	38.000	36.11
	Pattern	Ni	7440-02-0	0.500	0.48
	Resist ink	Resin		9.640	9.16
Capacitor	Capacitor	Ag	7440-22-4	1.780	7.66
	Capacitor	Ni	7440-02-0	0.185	0.80
	Capacitor	Pd	7440-53-3	4.880	21.01
	Capacitor	Sn	7440-31-5	0.185	0.80
	Capacitor	TiO2	13463-67-7	16.200	69.74
Crystal unit	Adhesive	Ag	7440-22-4	0.370	0.59
	Adhesive	Silicon Resin	7631-86-9	0.125	0.20
	Ceramic	Al2O3	1344-28-1	28.200	44.81
	Ceramic	CaO	1305-78-8	0.110	0.17
	Ceramic	Cr2O3 (Non hex)	1308-38-9	1.200	1.91
	Ceramic	MgO	1309-48-4	0.160	0.25
	Ceramic	SiO2	14808-60-7	1.120	1.78
	Ceramic	TiO2	13463-67-7	0.310	0.49
	Crystal Electrode	Au	7440-57-5	0.049	0.08
	Crystal Electrode	Cr	7440-47-3	0.001	0.00
	Crystal blank	SiO2	14808-60-7	1.508	2.40
	Gold Plate	Au	7440-57-5	0.280	0.44
	Kovar	Co	7440-48-4	1.539	2.45
	Kovar	Fe	7439-89-6	4.320	6.86
	Kovar	Ni	7440-02-0	2.625	4.17
	Metal layer	Mo	7439-98-7	0.190	0.30
	Metal layer	W	7440-33-7	6.210	9.87
	Nickel Plate	Co	7440-48-4	0.200	0.32
	Nickel Plate	Ni	7440-02-0	0.800	1.27
	Nickel plating	Ni	7440-02-0	0.427	0.68
	Seal Ring	Co	7440-48-4	1.950	3.10
	Seal Ring	Fe	7439-89-6	6.200	9.85
	Seal Ring	Ni	7440-02-0	3.330	5.29
Silver solder	Ag	7440-22-4	1.450	2.30	
Silver solder	Cu	7440-50-8	0.260	0.41	
Lid	German Silver	Cu	7440-50-8	126.000	57.14
	German Silver	Ni	7440-02-0	42.000	19.05
	German Silver	Zn	7440-66-6	52.500	23.81
Resistor	Alumina board	Al2O3	1344-28-1	3.143	82.56
	Alumina board	SiO2	14808-60-7	0.097	2.55
	Plating	Ni	7440-02-0	0.086	2.26

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Resistor	Plating	Ni	7440-02-0	0.086	2.26
	Plating	Sn	7440-31-5	0.086	2.26
	Protective glass	Al ₂ O ₃	1344-28-1	0.002	0.05
	Protective glass	B ₂ O ₃	1303-86-2	0.007	0.18
	Protective glass	PbO	1317-36-8	0.033	0.87
	Protective glass	PbO	1317-36-8	0.033	0.87
	Protective glass	SiO ₂	14808-60-7	0.018	0.47
	Resistance paste	Al ₂ O ₃	1344-28-1	0.001	0.03
	Resistance paste	B ₂ O ₃	1303-86-2	0.005	0.13
	Resistance paste	PbO	1317-36-8	0.026	0.68
	Resistance paste	SiO ₂	14808-60-7	0.014	0.37
	Resistor paste	RuO ₂	12036-10-1	0.013	0.34
	Terminal paste	Ag	7440-22-4	0.047	1.23
	Terminal paste	PbO	1317-36-8	0.005	0.13
	Terminal paste	Pd	7440-53-3	0.004	0.11
	Terminal paste	SiO ₂	14808-60-7	0.004	0.11
	Terminal paste	SiO ₂	14808-60-7	0.097	2.55
Solder cream	Solder cream	Ag	7440-22-4	0.600	3.00
	Solder cream	Cu	7440-50-8	0.100	0.50
	Solder cream	Sn	7440-31-5	19.300	96.50
Thermistor	Base Plating	Ni	7440-02-0	0.196	7.00
	Electrode	Ag	7440-22-4	0.280	10.00
	Electrode	Pd	7440-53-3	0.030	1.07
	Element	Co ₃ O ₄	1308-06-1	1.010	36.07
	Element	Mn ₃ O ₄	1317-35-7	0.640	22.86
	Finish Plating	Sn	7440-31-5	0.364	13.00
	Glass	B ₂ O ₃	1303-86-2	0.006	0.21
	Glass	Cr ₂ O ₃ (Non hex)	1308-38-9	0.016	0.57
	Glass	PbO	1317-36-8	0.162	5.79
	Glass	SiO ₂	14808-60-7	0.096	3.43
Transistor	Element	Au	7440-57-5	0.010	0.18
	Element	Si	7440-21-3	0.096	1.71
	Frame	Cu	7440-50-8	0.252	4.50
	Frame	Fe	7439-89-6	1.100	19.65
	Frame	Ni	7440-02-0	0.782	13.97
	Frame	Other		0.022	0.39
	Others	Other		0.024	0.43
	Plating	Cu	7440-50-8	0.005	0.09
	Plating	Sn	7440-31-5	0.245	4.38
	Resin exterior	Azo compound		0.015	0.27
	Resin exterior	Cr	7440-47-3	0.001	0.02
	Resin exterior	Epoxy resin bromide	68541-56-0	0.106	1.89

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Transistor	Resin exterior	Organic phosphorus		0.015	0.27
	Resin exterior	Other		0.742	13.25
	Resin exterior	Sb2O3	1309-64-4	0.033	0.59
	Resin exterior	Si compound		2.130	38.04
	Wire	Au	7440-57-5	0.021	0.38
Trimmer capacitor	Alloy	Other		1.793	20.38
	Alloy	Other		1.966	22.34
	Ceramic	Al2O3	1344-28-1	4.787	54.40
	Plate	Ni	7440-02-0	0.005	0.06
	Plate	Si compound		0.018	0.20
	Plating	Ag	7440-22-4	0.201	2.28
	Plating	Ni	7440-02-0	0.013	0.15
	Plating	Sn	7440-31-5	0.017	0.19
Total Mass:				452.910 mg	

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